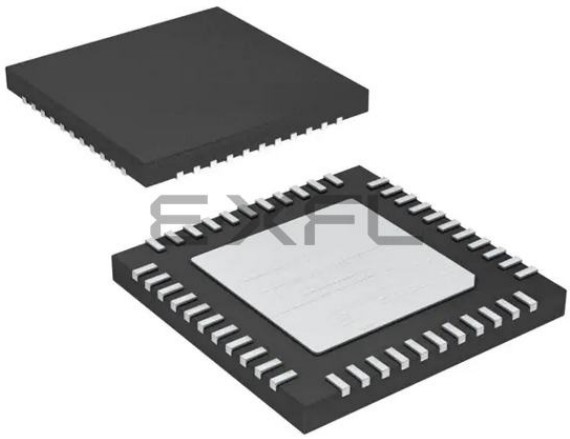

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	38
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 16x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24fv32ka304t-i-ml

TABLE 1-3: PIC24FV32KA304 FAMILY PINOUT DESCRIPTIONS

Function	F					FV					I/O	Buffer	Description
	Pin Number					Pin Number							
	20-Pin PDIP/ SSOP/ SOIC	28-Pin SPDIP/ SSOP/ SOIC	28-Pin QFN	44-Pin QFN/ TQFP	48-Pin UQFN	20-Pin PDIP/ SSOP/ SOIC	28-Pin SPDIP/ SSOP/ SOIC	28-Pin QFN	44-Pin QFN/ TQFP	48-Pin UQFN			
AN0	2	2	27	19	21	2	2	27	19	21	I	ANA	A/D Analog Inputs
AN1	3	3	28	20	22	3	3	28	20	22	I	ANA	
AN2	4	4	1	21	23	4	4	1	21	23	I	ANA	
AN3	5	5	2	22	24	5	5	2	22	24	I	ANA	
AN4	6	6	3	23	25	6	6	3	23	25	I	ANA	
AN5	—	7	4	24	26	—	7	4	24	26	I	ANA	
AN6	—	—	—	25	27	—	—	—	25	27	I	ANA	
AN7	—	—	—	26	28	—	—	—	26	28	I	ANA	
AN8	—	—	—	27	29	—	—	—	27	29	I	ANA	
AN9	18	26	23	15	16	18	26	23	15	16	I	ANA	
AN10	17	25	22	14	15	17	25	22	14	15	I	ANA	
AN11	16	24	21	11	12	16	24	21	11	12	I	ANA	
AN12	15	23	20	10	11	15	23	20	10	11	I	ANA	
AN13	7	9	6	30	33	7	9	6	30	33	I	ANA	
AN14	8	10	7	31	34	8	10	7	31	34	I	ANA	
AN15	9	11	8	33	36	9	11	8	33	36	I	ANA	
ASCL1	—	15	12	42	46	—	15	12	42	46	I/O	I^2C™	Alternate I2C1 Clock Input/Output
ASDA1	—	14	11	41	45	—	14	11	41	45	I/O	I^2C	Alternate I2C1 Data Input/Output
AV_{DD}	20	28	25	17	18	20	28	25	17	18	I	ANA	A/D Supply Pins
AV_{SS}	19	27	24	16	17	19	27	24	16	17	I	ANA	
C1INA	8	7	4	24	26	8	7	4	24	26	I	ANA	Comparator 1 Input A (+)
C1INB	7	6	3	23	25	7	6	3	23	25	I	ANA	Comparator 1 Input B (-)
C1INC	5	5	2	22	24	5	5	2	22	24	I	ANA	Comparator 1 Input C (+)
C1IND	4	4	1	21	23	4	4	1	21	23	I	ANA	Comparator 1 Input D (-)
C1OUT	17	25	22	14	15	17	25	22	14	15	O	—	Comparator 1 Output
C2INA	5	5	2	22	24	5	5	2	22	24	I	ANA	Comparator 2 Input A (+)
C2INB	4	4	1	21	23	4	4	1	21	23	I	ANA	Comparator 2 Input B (-)
C2INC	8	7	4	24	26	8	7	4	24	26	I	ANA	Comparator 2 Input C (+)
C2IND	7	6	3	23	25	7	6	3	23	25	I	ANA	Comparator 2 Input D (-)
C2OUT	14	20	17	7	7	11	16	13	43	47	O	—	Comparator 2 Output

5.5.1 PROGRAMMING ALGORITHM FOR FLASH PROGRAM MEMORY

The user can program one row of Flash program memory at a time by erasing the programmable row. The general process is as follows:

1. Read a row of program memory (32 instructions) and store in data RAM.
2. Update the program data in RAM with the desired new data.
3. Erase a row (see Example 5-1):
   a) Set the NVMOPx bits (NVMCON<5:0>) to '011000' to configure for row erase. Set the ERASE (NVMCON<6>) and WREN (NVMCON<14>) bits.
   b) Write the starting address of the block to be erased into the TBLPAG and W registers.
   c) Write 55h to NVMKEY.
   d) Write AAh to NVMKEY.
   e) Set the WR bit (NVMCON<15>). The erase cycle begins and the CPU stalls for the duration of the erase cycle. When the erase is done, the WR bit is cleared automatically.
4. Write the first 32 instructions from data RAM into the program memory buffers (see Example 5-1).
5. Write the program block to Flash memory:
   a) Set the NVMOPx bits to '011000' to configure for row programming. Clear the ERASE bit and set the WREN bit.
   b) Write 55h to NVMKEY.
   c) Write AAh to NVMKEY.
   d) Set the WR bit. The programming cycle begins and the CPU stalls for the duration of the write cycle. When the write to Flash memory is done, the WR bit is cleared automatically.

For protection against accidental operations, the write initiate sequence for NVMKEY must be used to allow any erase or program operation to proceed. After the programming command has been executed, the user must wait for the programming time until programming is complete. The two instructions following the start of the programming sequence should be NOPs, as shown in Example 5-5.

EXAMPLE 5-1: ERASING A PROGRAM MEMORY ROW – ASSEMBLY LANGUAGE CODE

```
; Set up NVMCON for row erase operation
        MOV     #0x4058, W0                 ;
        MOV     W0, NVMCON                  ; Initialize NVMCON
; Init pointer to row to be ERASED
        MOV     #tblpage(PROG_ADDR), W0     ;
        MOV     W0, TBLPAG                  ; Initialize PM Page Boundary SFR
        MOV     #tbloffset(PROG_ADDR), W0   ; Initialize in-page EA[15:0] pointer
        TBLWTL  W0, [W0]                    ; Set base address of erase block
        DISI    #5                          ; Block all interrupts
                                              for next 5 instructions
        MOV     #0x55, W0
        MOV     W0, NVMKEY                  ; Write the 55 key
        MOV     #0xAA, W1                   ;
        MOV     W1, NVMKEY                  ; Write the AA key
        BSET    NVMCON, #WR                 ; Start the erase sequence
        NOP                                 ; Insert two NOPs after the erase
        NOP                                 ; command is asserted
```

EXAMPLE 5-2: ERASING A PROGRAM MEMORY ROW – 'C' LANGUAGE CODE

```
// C example using MPLAB C30

    int __attribute__ ((space(auto_psv))) progAddr = 0x1234;// Global variable located in Pgm Memory
    unsigned int offset;

//Set up pointer to the first memory location to be written

    TBLPAG = __builtin_tblpage(&progAddr);              // Initialize PM Page Boundary SFR
    offset = __builtin_tbloffset(&progAddr);            // Initialize lower word of address

    __builtin_tblwtl(offset, 0x0000);                   // Set base address of erase block
                                                        // with dummy latch write

    NVMCON = 0x4058;                                    // Initialize NVMCON

    asm("DISI #5");                                     // Block all interrupts for next 5
                                                        // instructions
    __builtin_write_NVM();                              // C30 function to perform unlock
                                                        // sequence and set WR
```

EXAMPLE 5-3: LOADING THE WRITE BUFFERS – ASSEMBLY LANGUAGE CODE

```
; Set up NVMCON for row programming operations
       MOV     #0x4004, W0                  ;
       MOV     W0, NVMCON                   ; Initialize NVMCON
; Set up a pointer to the first program memory location to be written
; program memory selected, and writes enabled
       MOV     #0x0000, W0                  ;
       MOV     W0, TBLPAG                   ; Initialize PM Page Boundary SFR
       MOV     #0x6000, W0                  ; An example program memory address
; Perform the TBLWT instructions to write the latches
; 0th_program_word
       MOV     #LOW_WORD_0, W2              ;
       MOV     #HIGH_BYTE_0, W3             ;
       TBLWTL  W2, [W0]                     ; Write PM low word into program latch
       TBLWTH  W3, [W0++]                   ; Write PM high byte into program latch
; 1st_program_word
       MOV     #LOW_WORD_1, W2              ;
       MOV     #HIGH_BYTE_1, W3             ;
       TBLWTL  W2, [W0]                     ; Write PM low word into program latch
       TBLWTH  W3, [W0++]                   ; Write PM high byte into program latch
;  2nd_program_word
       MOV     #LOW_WORD_2, W2              ;
       MOV     #HIGH_BYTE_2, W3             ;
       TBLWTL  W2, [W0]                     ; Write PM low word into program latch
       TBLWTH  W3, [W0++]                   ; Write PM high byte into program latch
       •
       •
       •
; 32nd_program_word
       MOV     #LOW_WORD_31, W2             ;
       MOV     #HIGH_BYTE_31, W3            ;
       TBLWTL  W2, [W0]                     ; Write PM low word into program latch
       TBLWTH  W3, [W0]                     ; Write PM high byte into program latch
```

REGISTER 8-12: IEC1: INTERRUPT ENABLE CONTROL REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	U-0
U2TXIE	U2RXIE	INT2IE	T5IE	T4IE	—	OC3IE	—
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	INT1IE	CNIE	CMIE	MI2C1IE	SI2C1IE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **U2TXIE:** UART2 Transmitter Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 14 **U2RXIE:** UART2 Receiver Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 13 **INT2IE:** External Interrupt 2 Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 12 **T5IE:** Timer5 Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 11 **T4IE:** Timer4 Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 10 **Unimplemented:** Read as '0'

bit 9 **OC3IE:** Output Compare 3 Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 8-5 **Unimplemented:** Read as '0'

bit 4 **INT1IE:** External Interrupt 1 Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 3 **CNIE:** Input Change Notification Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 2 **CMIE:** Comparator Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 1 **MI2C1IE:** Master I2C1 Event Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 0 **SI2C1IE:** Slave I2C1 Event Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

REGISTER 8-23: IPC6: INTERRUPT PRIORITY CONTROL REGISTER 6

U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	T4IP2	T4IP1	T4IP0	—	—	—	—
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	OC3IP2	OC3IP1	OC3IP0	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **T4IP<2:0>:** Timer4 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11-7 **Unimplemented:** Read as '0'

bit 6-4 **OC3IP<2:0>:** Output Compare Channel 3 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3-0 **Unimplemented:** Read as '0'

REGISTER 8-25: IPC8: INTERRUPT PRIORITY CONTROL REGISTER 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	SPI2IP2	SPI2IP1	SPI2IP0	—	SPF2IP2	SPF2IP1	SPF2IP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-7 **Unimplemented:** Read as ‘0’

bit 6-4 **SPI2IP<2:0>:** SPI2 Event Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as ‘0’

bit 2-0 **SPF2IP<2:0>:** SPI2 Fault Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

REGISTER 9-1: OSCCON: OSCILLATOR CONTROL REGISTER (CONTINUED)

bit 7 **CLKLOCK:** Clock Selection Lock Enabled bit
If FSCM is enabled (FCKSM1 = 1):
1 = Clock and PLL selections are locked
0 = Clock and PLL selections are not locked and may be modified by setting the OSWEN bit
If FSCM is disabled (FCKSM1 = 0):
Clock and PLL selections are never locked and may be modified by setting the OSWEN bit.

bit 6 **Unimplemented:** Read as '0'

bit 5 **LOCK:** PLL Lock Status bit(2)
1 = PLL module is in lock or PLL module start-up timer is satisfied
0 = PLL module is out of lock, PLL start-up timer is running or PLL is disabled

bit 4 **Unimplemented:** Read as '0'

bit 3 **CF:** Clock Fail Detect bit
1 = FSCM has detected a clock failure
0 = No clock failure has been detected

bit 2 **SOSCDRV**: Secondary Oscillator Drive Strength bit(3)
1 = High-power SOSC circuit is selected
0 = Low/high-power select is done via the SOSCSRC Configuration bit

bit 1 **SOSCEN:** 32 kHz Secondary Oscillator (SOSC) Enable bit
1 = Enables the secondary oscillator
0 = Disables the secondary oscillator

bit 0 **OSWEN:** Oscillator Switch Enable bit
1 = Initiates an oscillator switch to the clock source specified by the NOSC<2:0> bits
0 = Oscillator switch is complete

Note 1: Reset values for these bits are determined by the FNOSCx Configuration bits.
2: This bit also resets to '0' during any valid clock switch or whenever a non-PLL Clock mode is selected.
3: When SOSC is selected to run from a digital clock input, rather than an external crystal (SOSCSRC = 0), this bit has no effect.

10.0 POWER-SAVING FEATURES

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information, refer to the *"PIC24F Family Reference Manual"*, **"Section 39. Power-Saving Features with Deep Sleep"** (DS39727).

The PIC24FV32KA304 family of devices provides the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of circuits being clocked constitutes lower consumed power. All PIC24F devices manage power consumption in four different ways:

- Clock Frequency
- Instruction-Based Sleep, Idle and Deep Sleep modes
- Software Controlled Doze mode
- Selective Peripheral Control in Software

Combinations of these methods can be used to selectively tailor an application's power consumption, while still maintaining critical application features, such as timing-sensitive communications.

10.1 Clock Frequency and Clock Switching

PIC24F devices allow for a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSCx bits. The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 9.0 "Oscillator Configuration"**.

10.2 Instruction-Based Power-Saving Modes

PIC24F devices have two special power-saving modes that are entered through the execution of a special PWRSAV instruction. Sleep mode stops clock operation and halts all code execution; Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation. Deep Sleep mode stops clock operation, code execution and all peripherals, except RTCC and DSWDT. It also freezes I/O states and removes power to SRAM and Flash memory.

The assembly syntax of the PWRSAV instruction is shown in Example 10-1.

Note: SLEEP_MODE and IDLE_MODE are constants defined in the assembler include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to "wake-up".

10.2.1 SLEEP MODE

Sleep mode includes these features:

- The system clock source is shut down. If an on-chip oscillator is used, it is turned off.
- The device current consumption will be reduced to a minimum provided that no I/O pin is sourcing current.
- The I/O pin directions and states are frozen.
- The Fail-Safe Clock Monitor does not operate during Sleep mode since the system clock source is disabled.
- The LPRC clock will continue to run in Sleep mode if the WDT or RTCC with LPRC as the clock source is enabled.
- The WDT, if enabled, is automatically cleared prior to entering Sleep mode.
- Some device features or peripherals may continue to operate in Sleep mode. This includes items, such as the Input Change Notification on the I/O ports, or peripherals that use an external clock input. Any peripheral that requires the system clock source for its operation will be disabled in Sleep mode.

The device will wake-up from Sleep mode on any of these events:

- On any interrupt source that is individually enabled
- On any form of device Reset
- On a WDT time-out

On wake-up from Sleep, the processor will restart with the same clock source that was active when Sleep mode was entered.

EXAMPLE 10-1: PWRSAV INSTRUCTION SYNTAX

```
PWRSAV     #SLEEP_MODE    ; Put the device into SLEEP mode
PWRSAV     #IDLE_MODE     ; Put the device into IDLE mode
BSET       DSCON, #DSEN   ; Enable Deep Sleep
PWRSAV     #SLEEP_MODE    ; Put the device into Deep SLEEP mode
```

11.2.2 I/O PORT WRITE/READ TIMING

One instruction cycle is required between a port direction change or port write operation and a read operation of the same port. Typically, this instruction would be a NOP.

11.3 Input Change Notification (ICN)

The Input Change Notification function of the I/O ports allows the PIC24FV32KA304 family of devices to generate interrupt requests to the processor in response to a Change-of-State (COS) on selected input pins. This feature is capable of detecting input Change-of-States, even in Sleep mode, when the clocks are disabled. Depending on the device pin count, there are up to 23 external signals (CN0 through CN22) that may be selected (enabled) for generating an interrupt request on a Change-of-State.

There are six control registers associated with the ICN module. The CNEN1 and CNEN2 registers contain the interrupt enable control bits for each of the CN input pins. Setting any of these bits enables a CN interrupt for the corresponding pins.

Each CN pin also has a weak pull-up/pull-down connected to it. The pull-ups act as a current source that is connected to the pin. The pull-downs act as a current sink to eliminate the need for external resistors when push button or keypad devices are connected.

On any pin, only the pull-up resistor or the pull-down resistor should be enabled, but not both of them. If the push button or the keypad is connected to V_{DD}, enable the pull-down, or if they are connected to V_{SS}, enable the pull-up resistors. The pull-ups are enabled separately, using the CNPU1 and CNPU2 registers, which contain the control bits for each of the CN pins.

Setting any of the control bits enables the weak pull-ups for the corresponding pins. The pull-downs are enabled separately, using the CNPD1 and CNPD2 registers, which contain the control bits for each of the CN pins. Setting any of the control bits enables the weak pull-downs for the corresponding pins.

When the internal pull-up is selected, the pin uses V_{DD} as the pull-up source voltage. When the internal pull-down is selected, the pins are pulled down to V_{SS} by an internal resistor. Make sure that there is no external pull-up source/pull-down sink when the internal pull-ups/pull-downs are enabled.

Note:	Pull-ups and pull-downs on Change Notification pins should always be disabled whenever the port pin is configured as a digital output.

EXAMPLE 11-1: PORT WRITE/READ EXAMPLE

```
MOV   0xFF00, W0;          //Configure PORTB<15:8> as inputs and PORTB<7:0> as outputs
MOV   W0, TRISB;
NOP;                       //Delay 1 cycle
BTSS  PORTB, #13;          //Next Instruction

Equivalent 'C' Code
TRISB = 0xFF00;            //Configure PORTB<15:8> as inputs and PORTB<7:0> as outputs
NOP();                     //Delay 1 cycle
if(PORTBbits.RB13 == 1)    // execute following code if PORTB pin 13 is set.
{
}
```

EQUATION 16-1: RELATIONSHIP BETWEEN DEVICE AND SPIx CLOCK SPEED(1)

$$FSCK = \frac{FCY}{\text{Primary Prescaler} * \text{Secondary Prescaler}}$$

Note 1: Based on FCY = FOSC/2; Doze mode and PLL are disabled.

TABLE 16-1: SAMPLE SCKx FREQUENCIES(1,2)

FCY = 16 MHz		Secondary Prescaler Settings				
		1:1	2:1	4:1	6:1	8:1
Primary Prescaler Settings	1:1	Invalid	8000	4000	2667	2000
	4:1	4000	2000	1000	667	500
	16:1	1000	500	250	167	125
	64:1	250	125	63	42	31
FCY = 5 MHz						
Primary Prescaler Settings	1:1	5000	2500	1250	833	625
	4:1	1250	625	313	208	156
	16:1	313	156	78	52	39
	64:1	78	39	20	13	10

Note 1: Based on FCY = FOSC/2; Doze mode and PLL are disabled.

2: SCKx frequencies are indicated in kHz.

17.3 Setting Baud Rate When Operating as a Bus Master

To compute the Baud Rate Generator (BRG) reload value, use Equation 17-1.

EQUATION 17-1: COMPUTING BAUD RATE RELOAD VALUE(1)

$$FSCL = \frac{FCY}{I2CxBRG + 1 + \frac{FCY}{10,000,000}}$$

or

$$I2CxBRG = \left(\frac{FCY}{FSCL} - \frac{FCY}{10,000,000}\right) - 1$$

Note 1: Based on FCY = FOSC/2; Doze mode and PLL are disabled.

17.4 Slave Address Masking

The I2CxMSK register (Register 17-3) designates address bit positions as "don't care" for both 7-Bit and 10-Bit Addressing modes. Setting a particular bit location (= 1) in the I2CxMSK register causes the slave module to respond, whether the corresponding address bit value is '0' or '1'. For example, when I2CxMSK is set to '00100000', the slave module will detect both addresses: '0000000' and '00100000'.

To enable address masking, the Intelligent Peripheral Management Interface (IPMI) must be disabled by clearing the IPMIEN bit (I2C1CON<11>).

Note: As a result of changes in the I²C protocol, the addresses in Table 17-2 are reserved and will not be Acknowledged in Slave mode. This includes any address mask settings that include any of these addresses.

TABLE 17-1: I²C™ CLOCK RATES(1)

Required System FSCL	FCY	I2CxBRG Value		Actual FSCL
		(Decimal)	(Hexadecimal)	
100 kHz	16 MHz	157	9D	100 kHz
100 kHz	8 MHz	78	4E	100 kHz
100 kHz	4 MHz	39	27	99 kHz
400 kHz	16 MHz	37	25	404 kHz
400 kHz	8 MHz	18	12	404 kHz
400 kHz	4 MHz	9	9	385 kHz
400 kHz	2 MHz	4	4	385 kHz
1 MHz	16 MHz	13	D	1.026 MHz
1 MHz	8 MHz	6	6	1.026 MHz
1 MHz	4 MHz	3	3	0.909 MHz

Note 1: Based on FCY = FOSC/2; Doze mode and PLL are disabled.

TABLE 17-2: I²C™ RESERVED ADDRESSES(1)

Slave Address	R/$\overline{W}$ Bit	Description
0000 000	0	General Call Address(2)
0000 000	1	Start Byte
0000 001	x	CBus Address
0000 010	x	Reserved
0000 011	x	Reserved
0000 1xx	x	HS Mode Master Code
1111 1xx	x	Reserved
1111 0xx	x	10-Bit Slave Upper Byte(3)

Note 1: The address bits listed here will never cause an address match, independent of the address mask settings.

2: This address will be Acknowledged only if GCEN = 1.

3: A match on this address can only occur on the upper byte in 10-Bit Addressing mode.

20.1 User Interface

20.1.1 POLYNOMIAL INTERFACE

The CRC module can be programmed for CRC polynomials of up to the 32nd order, using up to 32 bits. Polynomial length, which reflects the highest exponent in the equation, is selected by the PLEN<4:0> bits (CRCCON2<4:0>).

The CRCXORL and CRCXORH registers control which exponent terms are included in the equation. Setting a particular bit includes that exponent term in the equation. Functionally, this includes an XOR operation on the corresponding bit in the CRC engine. Clearing this bit disables the XOR.

For example, consider two CRC polynomials, one is a 16-bit equation and the other is a 32-bit equation:

$$x16 + x12 + x5 + 1$$

and

$$x32 + x26 + x23 + x22 + x16 + x12 + x11 + x10 + x8 + x7 + x5 + x4 + x2 + x + 1$$

To program these polynomials into the CRC generator, set the register bits, as shown in Table 20-1.

Note that the appropriate positions are set to '1' to indicate that they are used in the equation (for example, X26 and X23). The 0 bit required by the equation is always XORed; thus, X0 is a don't care. For a polynomial of length, N, it is assumed that the *N*th bit will always be used, regardless of the bit setting. Therefore, for a polynomial length of 32, there is no 32nd bit in the CRCXOR register.

20.1.2 DATA INTERFACE

The module incorporates a FIFO that works with a variable data width. Input data width can be configured to any value, between 1 and 32 bits, using the DWIDTH<4:0> bits (CRCCON2<12:8>). When the data width is greater than 15, the FIFO is 4 words deep. When the DWIDTHx value is between 15 and 8, the FIFO is 8 words deep. When the DWIDTHx value is less than 8, the FIFO is 16 words deep.

The data for which the CRC is to be calculated must first be written into the FIFO. Even if the data width is less than 8, the smallest data element that can be written into the FIFO is one byte. For example, if the DWIDTHx value is 5, then the size of the data is DWIDTHx + 1 or 6. The data is written as a whole byte; the two unused upper bits are ignored by the module.

Once data is written into the MSb of the CRCDAT registers (that is, MSb as defined by the data width), the value of the VWORD<4:0> bits (CRCCON1<12:8>) increments by one. For example, if the DWIDTHx value is 24, the VWORDx bits will increment when bit 7 of CRCDATH is written. Therefore, CRCDATL must always be written before CRCDATH.

The CRC engine starts shifting data when the CRCGO bit is set and the value of the VWORDx bits is greater than zero. Each word is copied out of the FIFO into a buffer register, which decrements VWORDx. The data is then shifted out of the buffer. The CRC engine continues shifting at a rate of two bits per instruction cycle until the VWORDx value reaches zero. This means that for a given data width, it takes half that number of instructions for each word to complete the calculation. For example, it takes 16 cycles to calculate the CRC for a single word of 32-bit data.

When the VWORDx value reaches the maximum value for the configured value of DWIDTHx (4, 8 or 16), the CRCFUL bit becomes set. When the VWORDx value reaches zero, the CRCMPT bit becomes set. The FIFO is emptied and the VWORD<4:0> bits are set to '00000' whenever CRCEN is '0'.

At least one instruction cycle must pass, after a write to CRCDAT, before a read of the VWORDx bits is done.

TABLE 20-1: CRC SETUP EXAMPLES FOR 16 AND 32-BIT POLYNOMIAL

CRC Control Bits	Bit Values	
	16-Bit Polynomial	32-Bit Polynomial
PLEN<4:0>	01111	11111
X<31:16>	0000 0000 0000 000x	0000 0100 1100 0001
X<15:0>	0001 0000 0010 000x	0001 1101 1011 011x

To perform an A/D conversion:

1. Configure the A/D module:
   a) Configure the port pins as analog inputs and/or select band gap reference inputs (ANS<12:10>, ANS<5:0>).
   b) Select voltage reference source to match the expected range on the analog inputs (AD1CON2<15:13>).
   c) Select the analog conversion clock to match the desired data rate with the processor clock (AD1CON3<7:0>).
   d) Select the appropriate sample/conversion sequence (AD1CON1<7:4> and AD1CON3<12:8>).
   e) Select how conversion results are presented in the buffer (AD1CON1<9:8>).
   f) Select the interrupt rate (AD1CON2<6:2>).
   g) Turn on the A/D module (AD1CON1<15>).
2. Configure the A/D interrupt (if required):
   a) Clear the AD1IF bit.
   b) Select the A/D interrupt priority.

To perform an A/D sample and conversion using Threshold Detect scanning:

1. Configure the A/D module:
   a) Configure the port pins as analog inputs (ANS<12:10>, ANS<5,0>).
   b) Select the voltage reference source to match the expected range on the analog inputs (AD1CON2<15:13>).
   c) Select the analog conversion clock to match the desired data rate with the processor clock (AD1CON3<7:0>).
   d) Select the appropriate sample/conversion sequence (AD1CON1<7:4>, AD1CON3<12:8>).
   e) Select how the conversion results are presented in the buffer (AD1CON1<9:8>).
   f) Select the interrupt rate (AD1CON2<6:2>).
2. Configure the threshold compare channels:
   a) Enable auto-scan – ASEN bit (AD1CON5<15>).
   b) Select the Compare mode, “Greater Than, Less Than or Windowed” – CMx bits (AD1CON5<1:0>).
   c) Select the threshold compare channels to be scanned (ADCSSH, ADCSSL).
   d) If the CTMU is required as a current source for a threshold compare channel, enable the corresponding CTMU channel (ADCCTMUENH, ADCCTMUENL).
   e) Write the threshold values into the corresponding ADC1BUFn registers.
   f) Turn on the A/D module (AD1CON1<15>).

Note: If performing an A/D sample and conversion using Threshold Detect in Sleep Mode, the RC A/D clock source must be selected before entering into Sleep mode.

3. Configure the A/D interrupt (OPTIONAL):
   a) Clear the AD1IF bit.
   b) Select the A/D interrupt priority.

REGISTER 22-5: AD1CHS: A/D SAMPLE SELECT REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CH0NB2	CH0NB1	CH0NB0	CH0SB4	CH0SB3	CH0SB2	CH0SB1	CH0SB0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CH0NA2	CH0NA1	CH0NA0	CH0SA4	CH0SA3	CH0SA2	CH0SA1	CH0SA0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **CH0NB<2:0>:** Sample B Channel 0 Negative Input Select bits
111 = AN6(1)
110 = AN5(2)
101 = AN4
100 = AN3
011 = AN2
010 = AN1
001 = AN0
000 = AVSS

bit 12-8 **CH0SB<4:0>:** S/H Amplifier Positive Input Select for MUX B Multiplexer Setting bits
11111 = Unimplemented, do not use
11110 = AVDD
11101 = AVSS
11100 = Upper guardband rail (0.785 * VDD)
11011 = Lower guardband rail (0.215 * VDD)
11010 = Internal Band Gap Reference (VBG)(3)
11001-10010 = Unimplemented, do not use
10001 = No channels are connected, all inputs are floating (used for CTMU)
10000 = No channels are connected, all inputs are floating (used for CTMU temperature sensor input)
01111 = AN15
01110 = AN14
01101 = AN13
01100 = AN12
01011 = AN11
01010 = AN10
01001 = AN9
01000 = AN8(1)
00111 = AN7(1)
00110 = AN6(1)
00101 = AN5(2)
00100 = AN4
00011 = AN3
00010 = AN2
00001 = AN1
00000 = AN0

bit 7-5 **CH0NA<2:0>:** Sample A Channel 0 Negative Input Select bits
The same definitions as for CHONB<2:0>.

bit 4-0 **CH0SA<4:0>:** Sample A Channel 0 Positive Input Select bits
The same definitions as for CHONA<4:0>.

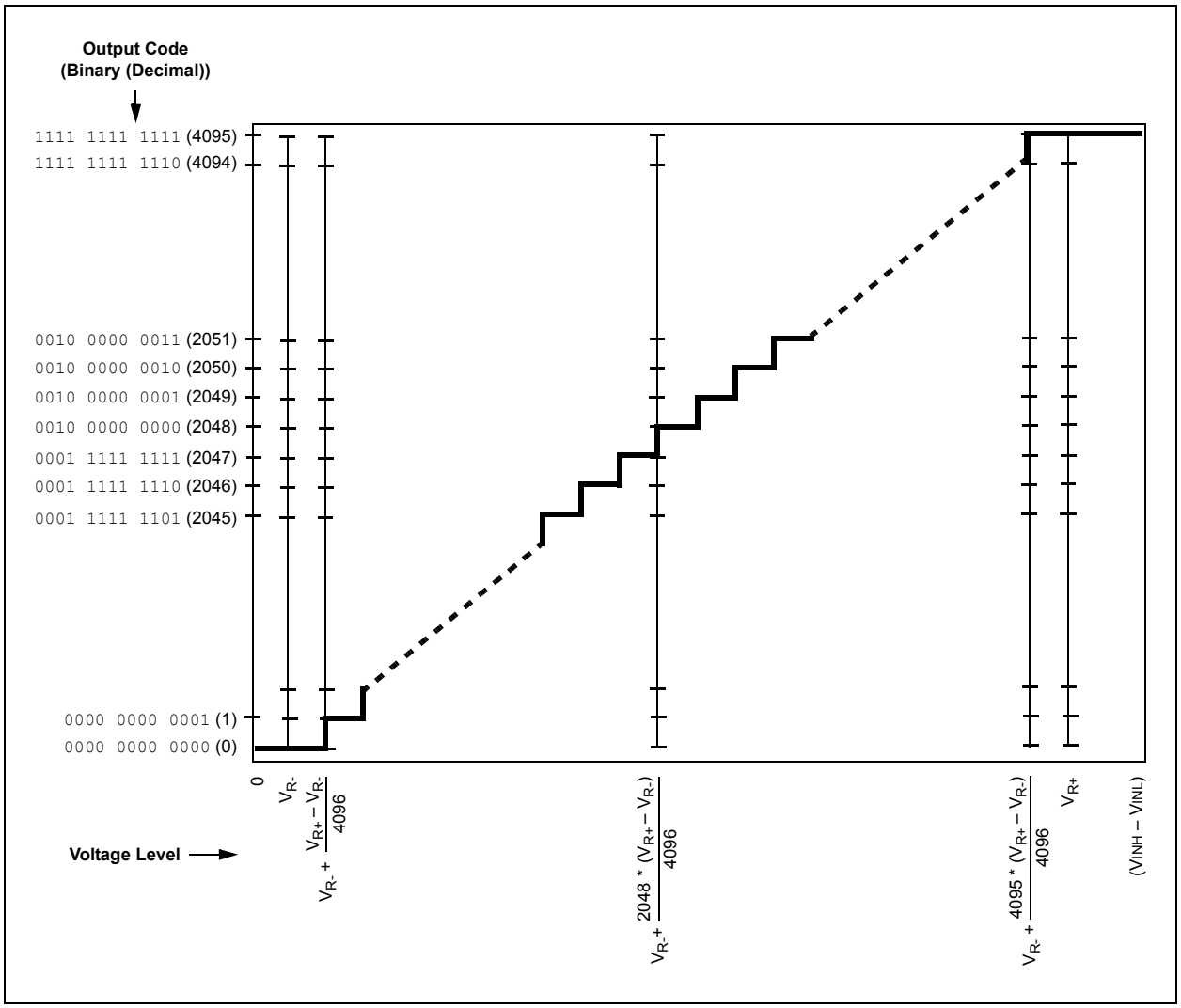
Note 1: This is implemented on 44-pin devices only.
2: This is implemented on 28-pin and 44-pin devices only.
3: The band gap value used for this input is 2x or 4x the internal VBG, which is selected when PVCFG<1:0> = 1x.

22.3 Transfer Function

The transfer functions of the A/D Converter in 12-bit resolution are shown in Figure 22-3. The difference of the input voltages, (V_{INH} – V_{INL}), is compared to the reference, ((V_{R+}) – (V_{R-})).

- The first code transition occurs when the input voltage is ((V_{R+}) – (V_{R-}))/4096 or 1.0 LSb.
- The `0000 0000 0001` code is centered at V_{R-} + (1.5 * ((V_{R+}) – (V_{R-}))/4096).
- The '`0010 0000 0000`' code is centered at V_{REFL} + (2048.5 * ((V_{R+}) – (V_{R-}))/4096).
- An input voltage less than V_{R-} + (((V_{R-}) – (V_{R-}))/4096) converts as '`0000 0000 0000`'.
- An input voltage greater than (V_{R-}) + (4095 ((V_{R+}) – (V_{R-}))/4096) converts as '`1111 1111 1111`'.

FIGURE 22-3: 12-BIT A/D TRANSFER FUNCTION



NOTES:

25.3 Pulse Generation and Delay

The CTMU module can also generate an output pulse with edges that are not synchronous with the device's system clock. More specifically, it can generate a pulse with a programmable delay from an edge event input to the module.

When the module is configured for pulse generation delay by setting the TGEN bit (CTMUCON<12>), the internal current source is connected to the B input of Comparator 2. A capacitor (CDELAY) is connected to the Comparator 2 pin, C2INB, and the Comparator Voltage Reference, CVREF, is connected to C2INA. CVREF is then configured for a specific trip point. The module begins to charge CDELAY when an edge event is detected. While CVREF is greater than the voltage on CDELAY, CTPLS is high.

When the voltage on CDELAY equals CVREF, CTPLS goes low. With Comparator 2 configured as the second edge, this stops the CTMU from charging. In this state event, the CTMU automatically connects to ground. The IDISSEN bit doesn't need to be set and cleared before the next CTPLS cycle.

Figure 25-3 illustrates the external connections for pulse generation, as well as the relationship of the different analog modules required. While CTED1 is shown as the input pulse source, other options are available. A detailed discussion on pulse generation with the CTMU module is provided in the "*PIC24F Family Reference Manual*".

FIGURE 25-3: TYPICAL CONNECTIONS AND INTERNAL CONFIGURATION FOR PULSE DELAY GENERATION

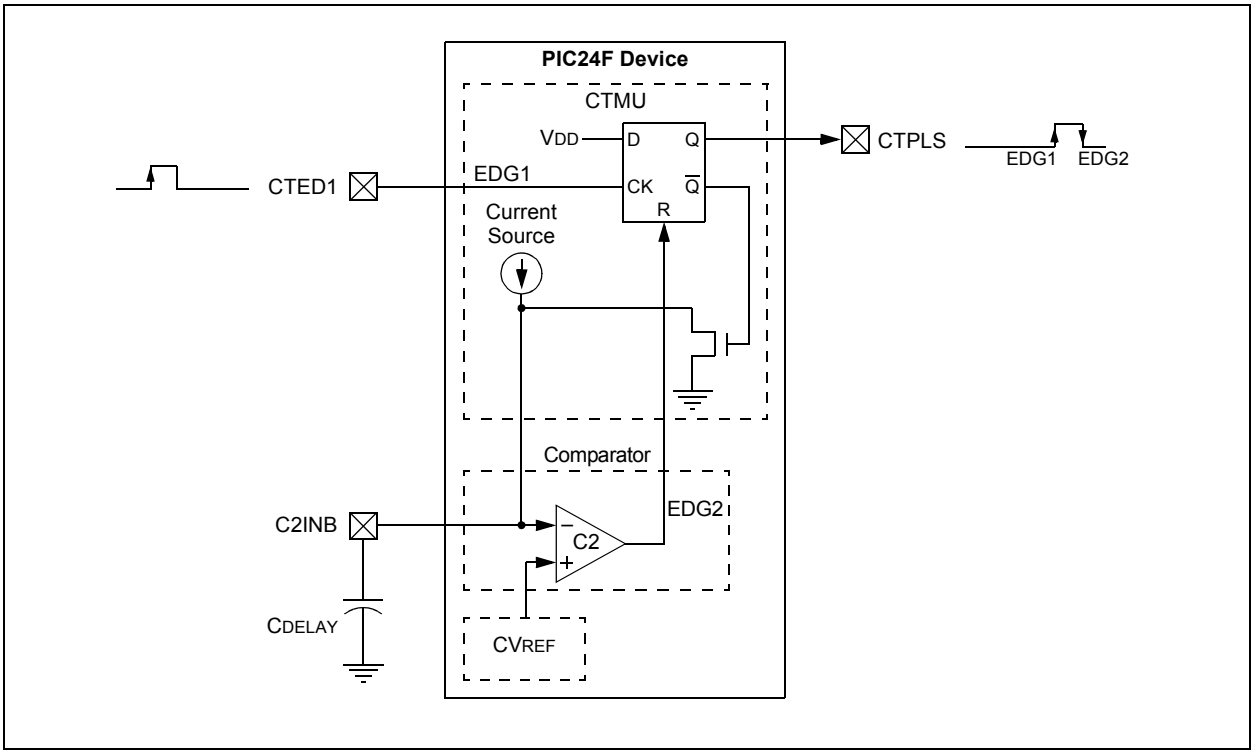
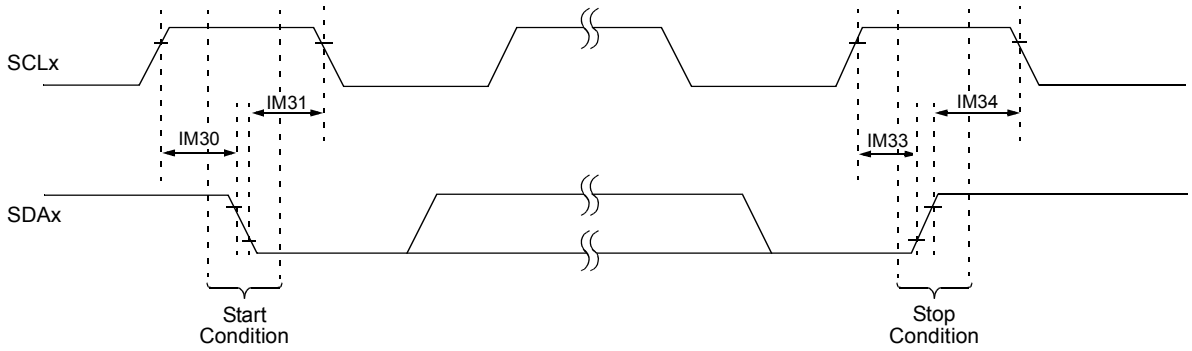


FIGURE 29-12: I²C™ BUS START/STOP BITS TIMING CHARACTERISTICS (MASTER MODE)



Note: Refer to Figure 29-3 for load conditions.

TABLE 29-31: I²C™ BUS START/STOP BIT TIMING REQUIREMENTS (MASTER MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial) -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic**		**Min(1)**	**Max**	**Units**	**Conditions**
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM34	THD:STO	Stop Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	ns	
			400 kHz mode	TCY/2 (BRG + 1)	—	ns	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	ns	

Note 1: BRG is the value of the I²C™ Baud Rate Generator. Refer to **Section 17.3 "Setting Baud Rate When Operating as a Bus Master"** for details.

2: Maximum pin capacitance = 10 pF for all I²C pins (for 1 MHz mode only).

FIGURE 30-30: VIL/VIH vs. VDD (OSCO, TEMPERATURES AS NOTED)

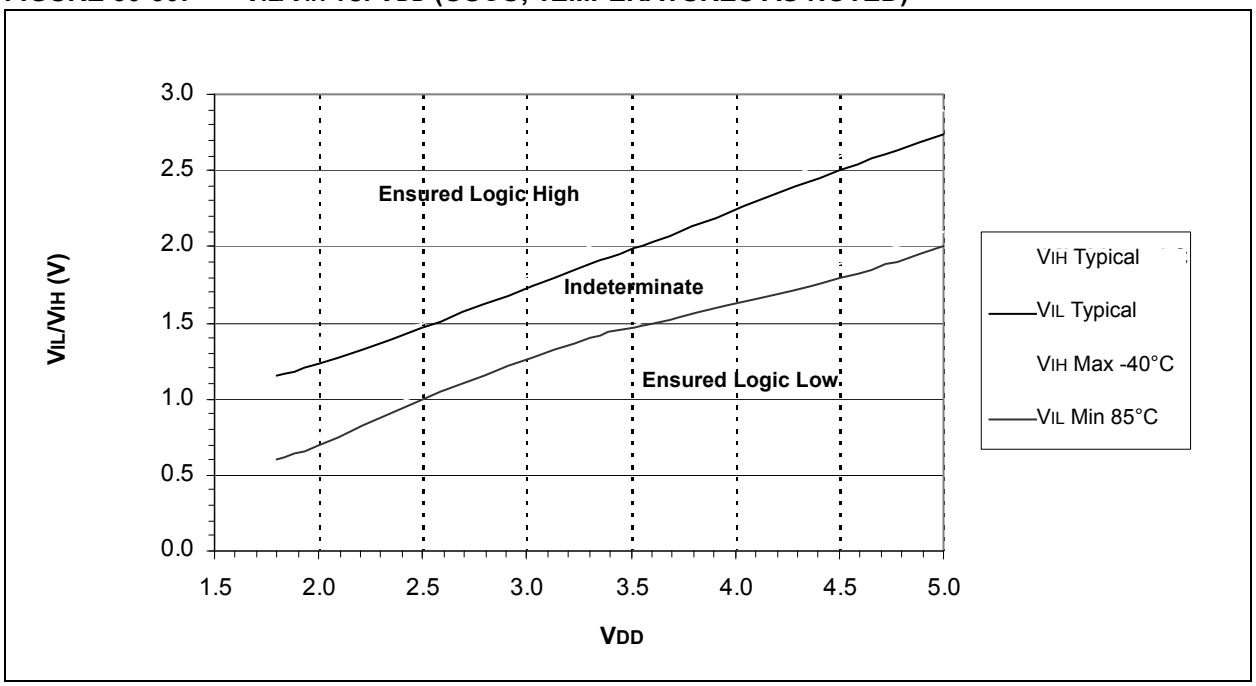
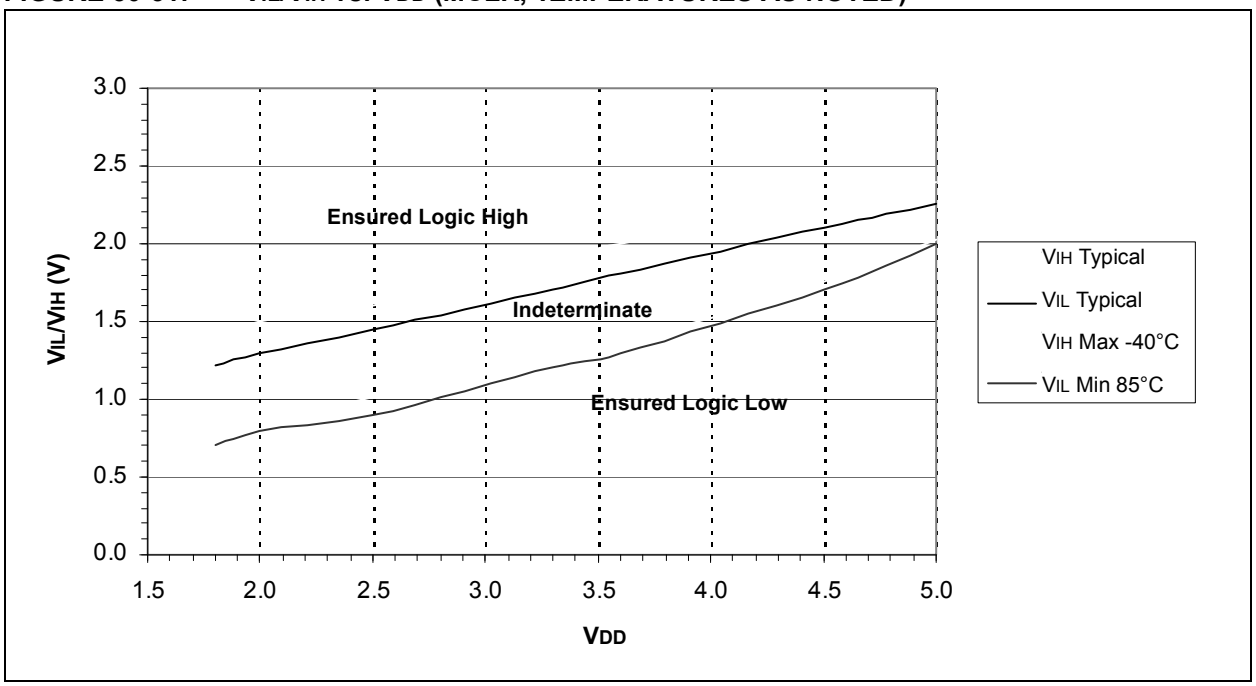
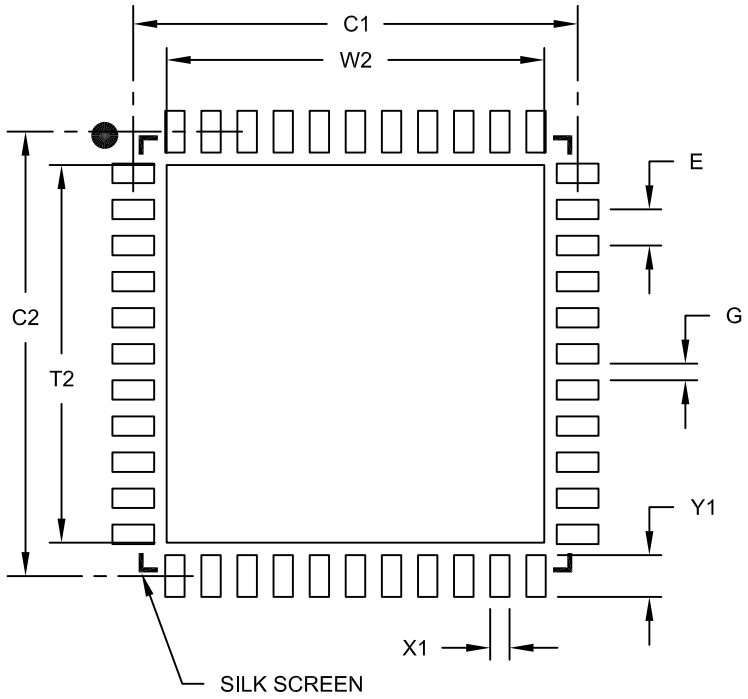


FIGURE 30-31: VIL/VIH vs. VDD ($\overline{\text{MCLR}}$, TEMPERATURES AS NOTED)



44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Optional Center Pad Width	W2			6.60
Optional Center Pad Length	T2			6.60
Contact Pad Spacing	C1		8.00	
Contact Pad Spacing	C2		8.00	
Contact Pad Width (X44)	X1			0.35
Contact Pad Length (X44)	Y1			0.85
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2103B